

Title (en)

ELECTROPLATING BATH FOR ELECTROCHEMICAL DEPOSITION OF A CU-SN-ZN-PD ALLOY LAYER, METHOD FOR ELECTROCHEMICAL DEPOSITION OF SAID ALLOY LAYER, SUBSTRATE COMPRISING SAID ALLOY LAYER AND USES OF THE COATED SUBSTRATE

Title (de)

GALVANIKBAD ZUR ELEKTROCHEMISCHEN ABSCHIEDUNG EINER CU-SN-ZN-PD LEGIERUNGSSCHICHT, VERFAHREN ZUR ELEKTROCHEMISCHEN ABSCHIEDUNG DER LEGIERUNGSSCHICHT, SUBSTRAT MIT DER LEGIERUNGSSCHICHT UND VERWENDUNGEN DES BESCHICHTETEN SUBSTRATS

Title (fr)

BAIN GALVANIQUE POUR LE DÉPÔT ÉLECTROCHIMIQUE D'UNE COUCHE D'ALLIAGE CU-SN-ZN-PD, PROCÉDÉ DE DÉPÔT ÉLECTROCHIMIQUE DE CETTE COUCHE D'ALLIAGE, SUBSTRAT COMPRENANT CETTE COUCHE D'ALLIAGE ET UTILISATIONS DU SUBSTRAT REVÊTU

Publication

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Application

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Priority

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Abstract (en)

[origin: EP3150744A1] The invention provides an electroplating bath for electrochemical deposition of a novel Cu-Sn-Zn-Pd alloy on a substrate. The novel alloy is characterized by exceptional corrosion resistance and the commonly used precious metal intermediate layer (e.g. a Pd-layer) between the substrate and the finishing layer is no longer necessary which allows a substantial reduction of the production costs of the plated substrates.

IPC 8 full level

C22C 9/02 (2006.01)

CPC (source: EP US)

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Citation (examination)

- WO 2017021916 A2 20170209 - BLUCLAD S R L [IT]
- JP 2977503 B2 19991115
- US 6780527 B2 20040824 - NAOI KOICHI [JP], et al

Citation (opposition)

Opponent : BLUCLAD S.p.A.

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- JP H10219467 A 19980818 - BIKUTORIA KK
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- DEPOTO ET AL.: "White Bronze, Copper-Tin-Zinc Tri-metal: Expanding Applications and New Developments in a Changing Landscape", 20 May 2013 (2013-05-20), XP055142805, Retrieved from the Internet <URL:https://www.pfonline.com/articles/white-bronze-copper-tin-zinc-tri-metal-expanding-applications-and-new-developments-in-a-changing-landscape>

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IT202000011203A1; IT201800004235A1; WO2021229481A1

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DOCDB simple family (publication)

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